



Material Content Data Sheet



Sales Product Name				BSZ100N03MS G		Issued		1. August 2018	
MA#				MA001314048					
Package				PG-TSDSON-8-1		Weight*		36.06 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.709	1.97	1.97	19660	19660	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		66		
	non noble metal	zinc	7440-66-6	0.009	0.03		263		
	non noble metal	iron	7439-89-6	0.189	0.53		5252		
wire	non noble metal	copper	7440-50-8	7.689	21.33	21.90	213255	218836	
	non noble metal	copper	7440-50-8	0.039	0.11	0.11	1074	1074	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1040	
	plastics	epoxy resin	-	1.930	5.35		53543		
	inorganic material	silicondioxide	60676-86-0	16.775	46.53	51.98	465247	519830	
leadfinish	non noble metal	tin	7440-31-5	0.370	1.03	1.03	10264	10264	
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2241	2241	
solder	non noble metal	tin	7440-31-5	0.021	0.06		579		
	noble metal	silver	7440-22-4	0.026	0.07		723		
	non noble metal	lead	7439-92-1	0.996	2.76	2.89	27630	28932	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33		
	non noble metal	zinc	7440-66-6	0.005	0.01		130		
	non noble metal	iron	7439-89-6	0.094	0.26		2607		
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.58	10.85	105836	108606	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		109		
	non noble metal	iron	7439-89-6	0.078	0.22		2173		
	non noble metal	copper	7440-50-8	3.182	8.82	9.05	88248	90557	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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